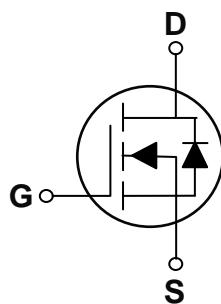
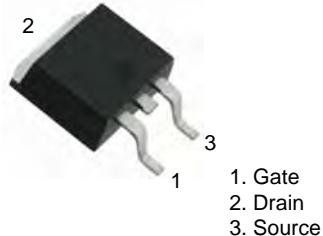


40V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO-252 Pin Configuration



BVDSS	RDS(ON)	ID
40V	5.5mΩ	80A

Features

- 40V, 80A, RDS(ON)=5.5mΩ @VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	80	A
I_D	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	50	A
I_{DM}	Drain Current – Pulsed ¹	320	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	88	W
P_D	Power Dissipation – Derate above 25°C	0.59	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.7	°C/W



FTK4904D

40V N-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.03	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=40\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=32\text{V}$, $V_{GS}=0\text{V}$, $T_J=85^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=20\text{A}$	---	4.2	5.5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=10\text{A}$	---	5.3	7	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.0	1.6	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=10\text{V}$, $I_D=10\text{A}$	---	16	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{DS}=32\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=10\text{A}$	---	25	50	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	6.4	13	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	12.1	24	
$T_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=20\text{V}$, $V_{GS}=10\text{V}$, $R_G=3.3\Omega$ $I_D=1\text{A}$	---	14.2	28	ns
T_r	Rise Time ^{2,3}		---	18.3	36	
$T_{d(off)}$	Turn-Off Delay Time ^{2,3}		---	38.8	76	
T_f	Fall Time ^{2,3}		---	13.9	28	
C_{iss}	Input Capacitance		---	2410	3600	pF
C_{oss}	Output Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	233	400	
C_{rss}	Reverse Transfer Capacitance		---	152	230	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	1.6	3.2	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	80	A
I_{SM}	Pulsed Source Current		---	---	160	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

40V N-Channel MOSFETs

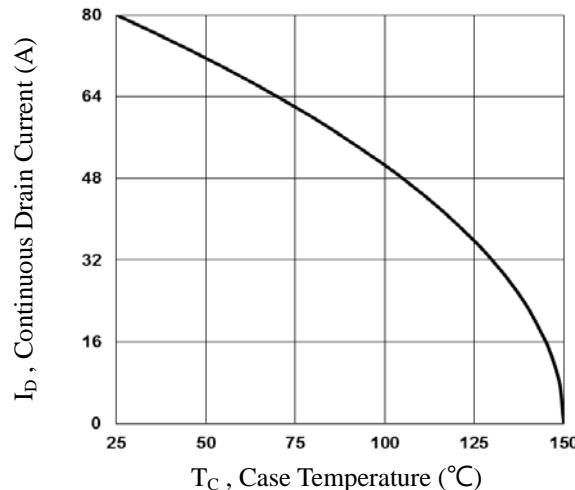


Fig.1 Continuous Drain Current vs. T_C

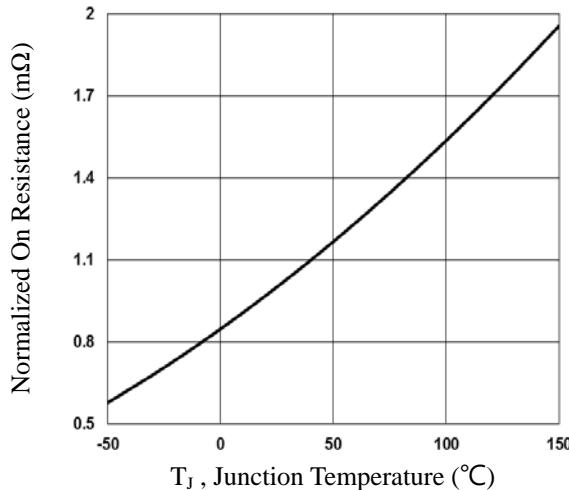


Fig.2 Normalized RDSON vs. T_J

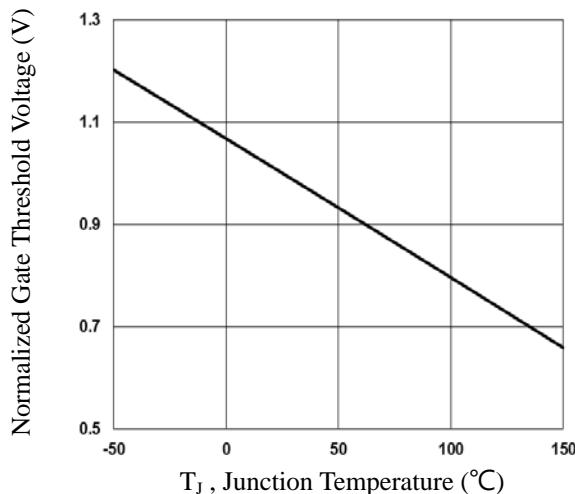


Fig.3 Normalized V_{th} vs. T_J

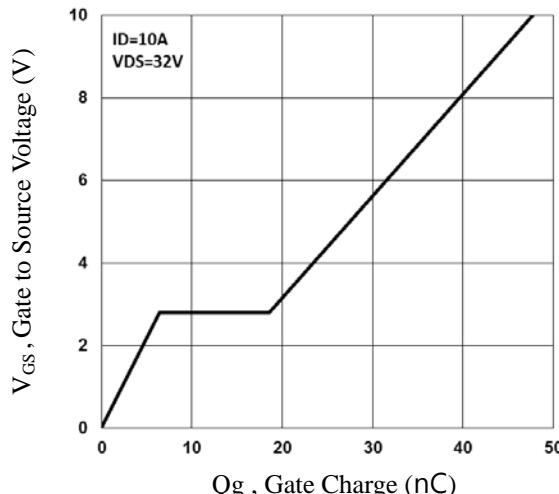


Fig.4 Gate Charge Waveform

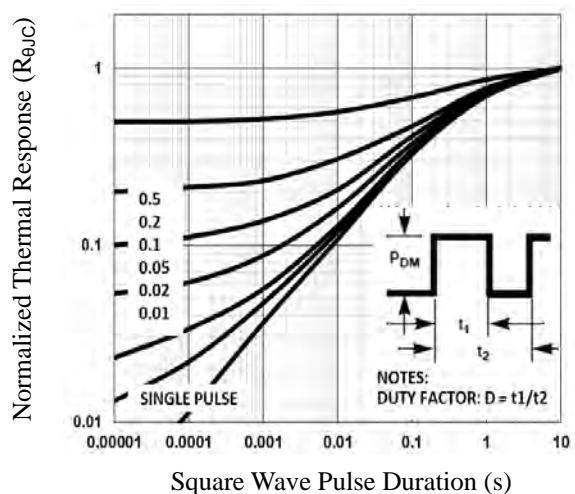


Fig.5 Normalized Transient Impedance

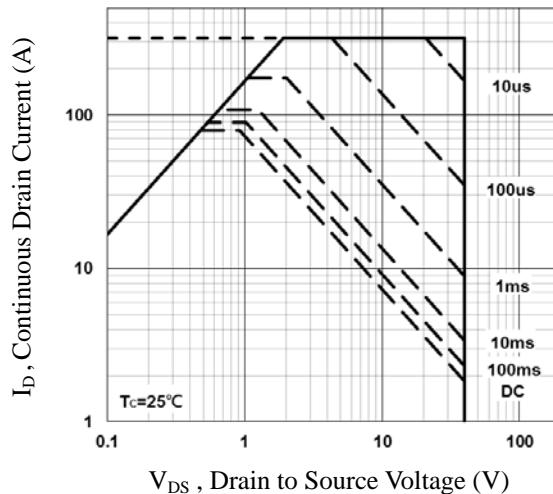


Fig.6 Maximum Safe Operation Area

40V N-Channel MOSFETs

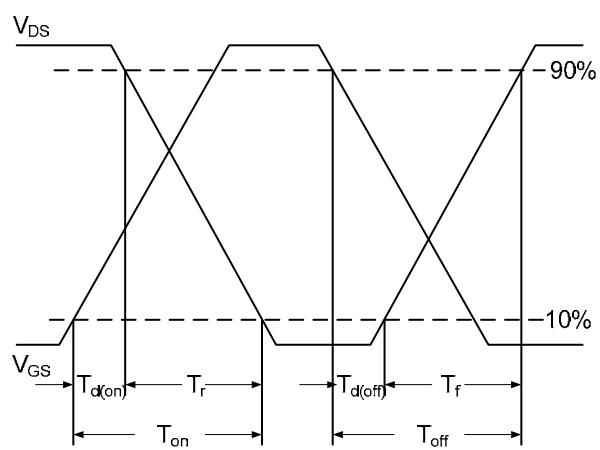


Fig.7 Switching Time Waveform

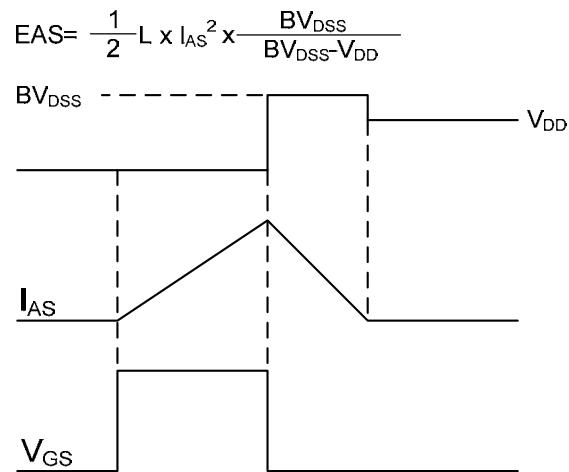
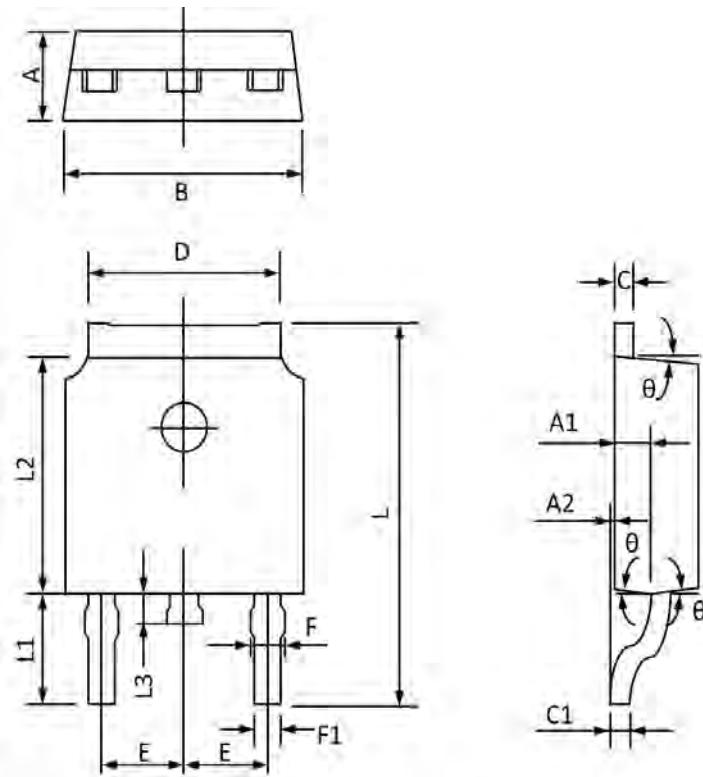


Fig.8 EAS Waveform

40V N-Channel MOSFETs

TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°